

24 GHz Transceiver: BGT24LTR11

Evaluation board and system design

About this document

Scope and purpose

This application note describes the features of Infineon's 24 GHz transceiver chipset, BGT24LTR11 MMIC and its evaluation board. It provides:

- Description of all the different building blocks of the MMIC
- Operation of the different blocks
- Measurement data showing behaviour over temperature
- VCO control using different methodologies – PTAT, PLL, and a software-based open loop

Intended audience

This document serves as a primer for users who want to get started with Infineon's low power BGT24LTR11 MMIC for 24 GHz radar.

Related documents

Additional information can be found on www.infineon.com/24GHz

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1 Introduction to BGT24LTR11

BGT24LTR11 is Silicon Germanium radar MMIC for signal generation and reception, operating in the 24.0 GHz to 24.25 GHz ISM band. It is based on a 24 GHz fundamental voltage controlled oscillator (VCO). The device was designed with Doppler-radar applications in mind—as it is capable of keeping the transmit signal inside the ISM band without any external PLL — and may also be used in other types of radar such as FMCW or FSK.

A built-in voltage source delivers a VCO tuning voltage which is proportional to absolute temperature (PTAT). When connected to the VCO tuning pin it compensates for the inherent frequency drift of the VCO over temperature thus stabilizing the VCO within the ISM band eliminating the need for a PLL/Microcontroller. An integrated 1:16 frequency divider also allows for external phase lock loop VCO frequency stabilization.

The receiver section uses a low noise amplifier (LNA) in front of a quadrature homodyne down-conversion mixer in order to provide excellent receiver sensitivity. Derived from the internal VCO signal, a RC-polyphase filter (PPF) generates quadrature LO signals for the quadrature mixer. I/Q IF outputs are available through single-ended terminals.

The device is manufactured in a 0.18 μm SiGe:C technology offering a cutoff frequency of 200 GHz. It is packaged in a 16-pin leadless RoHS compliant TSNP package.

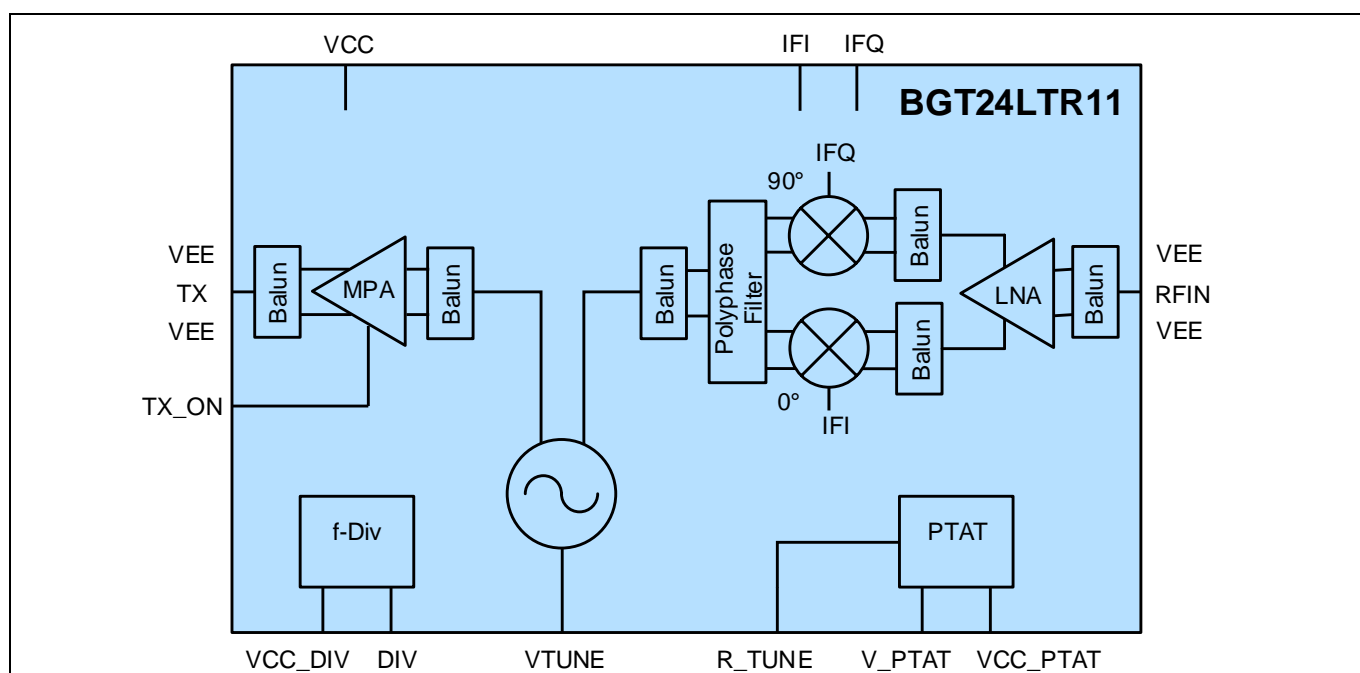


Figure 1 BGT24LTR11 Block Diagram

2 Building blocks

2.1 Transmitter

BGT24LTR11 has a single-ended transmitter output TX (pin 11) with a typical output power of 6 dBm. The transmitter's output may be enabled and disabled by applying appropriate voltages to TX_ON (pin 5) as shown in Table 1.

Disabling the TX output will not save power as the output will be switched to an internal load while the rest of the chip is still running. This is necessary in case one wants to implement a software controlled oscillator (see Section 4).

Table 1 Enabling/disabling TX output

Enable TX	Disable TX
Voltage at TX_ON > 2 V	Voltage at TX_ON < 0.8 V

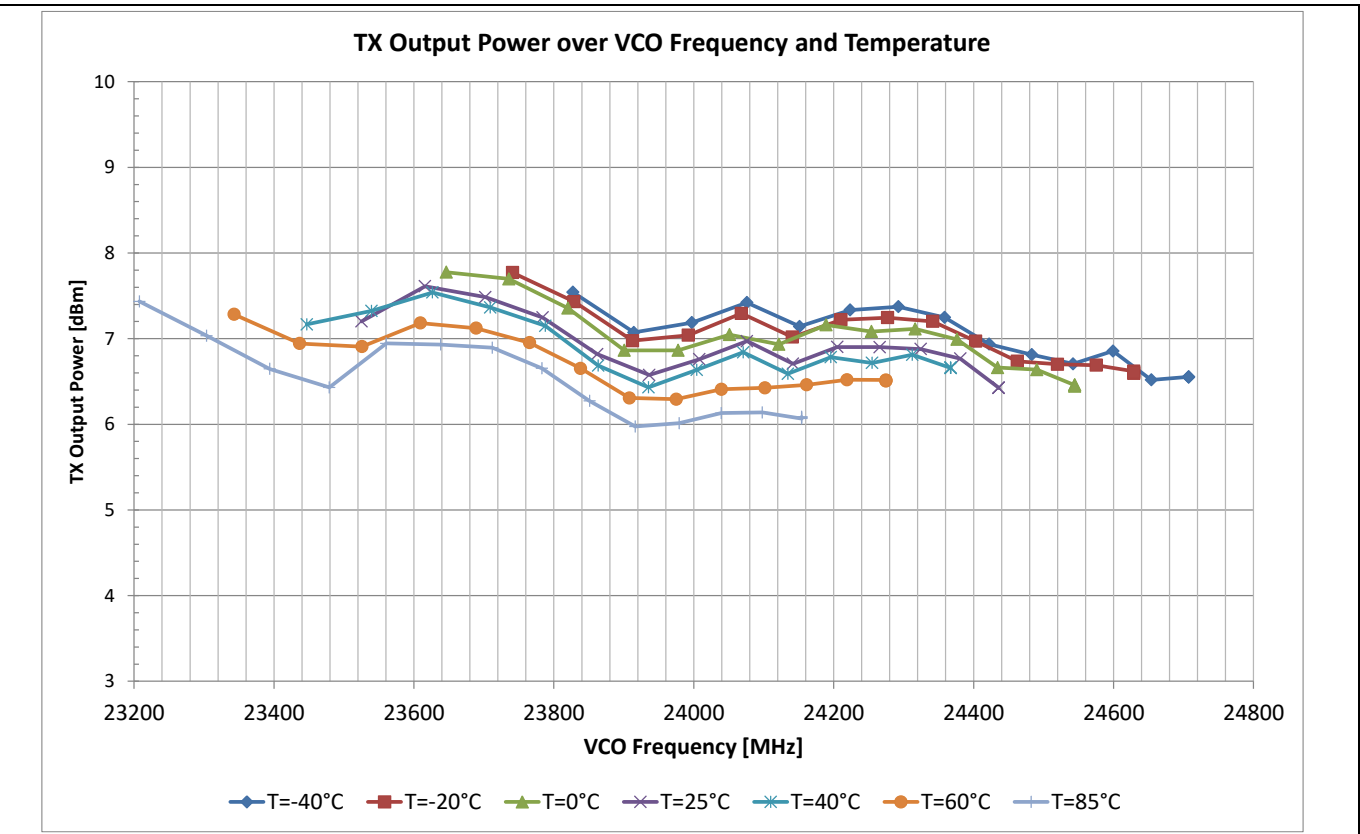


Figure 2 TX output power vs. frequency and temperature

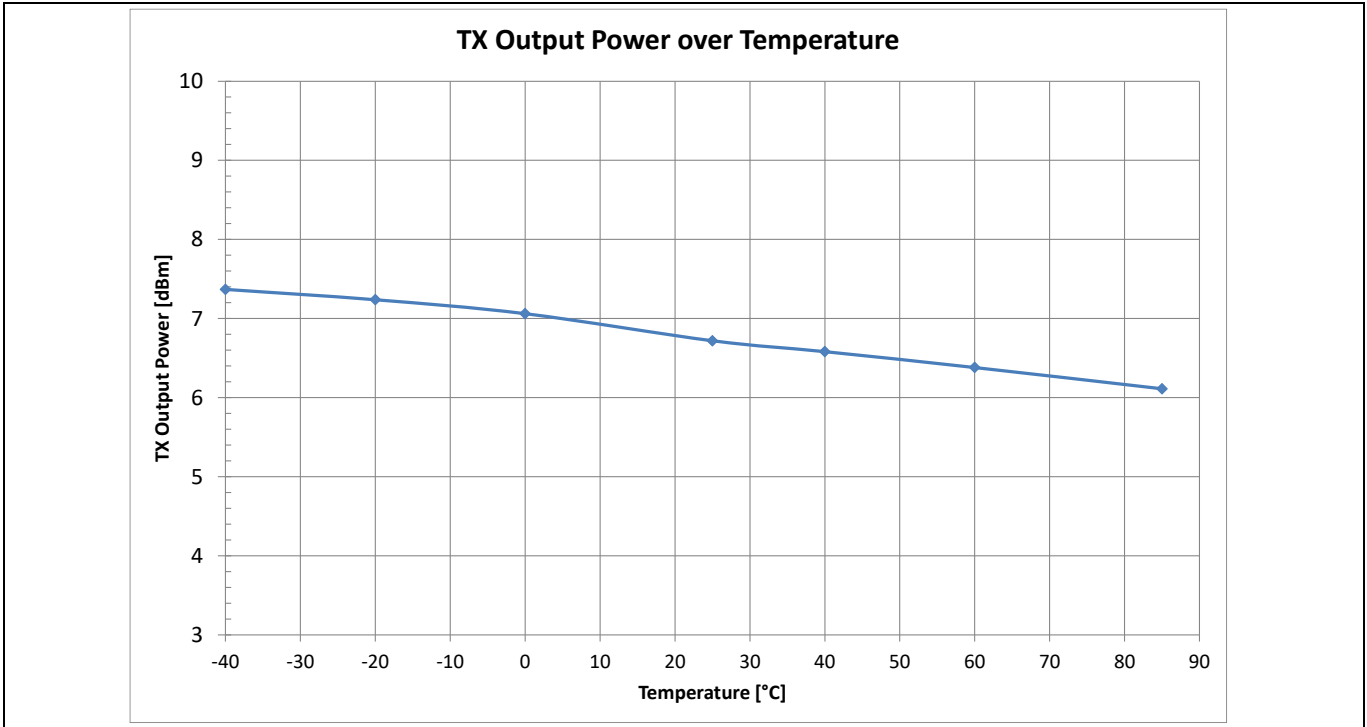


Figure 3 TX output power with VTUNE connected to V_PTAT

2.2 Receiver

The receiver consists of an LNA followed by quadrature direct-conversion mixer. Its input (RX, pin 3) is single-ended. The voltage conversion gain is typically 20 dB with a single side-band noise figure of 10 dB.

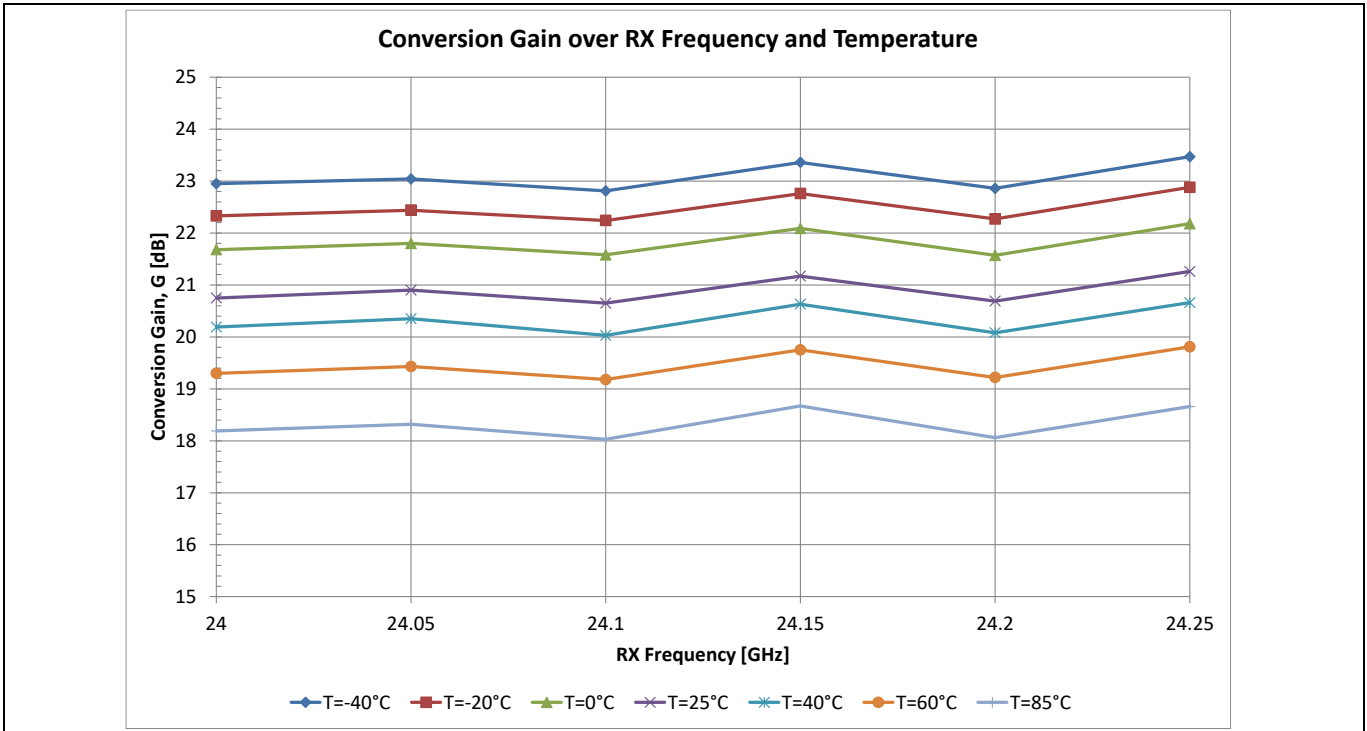


Figure 4 Gain vs. frequency

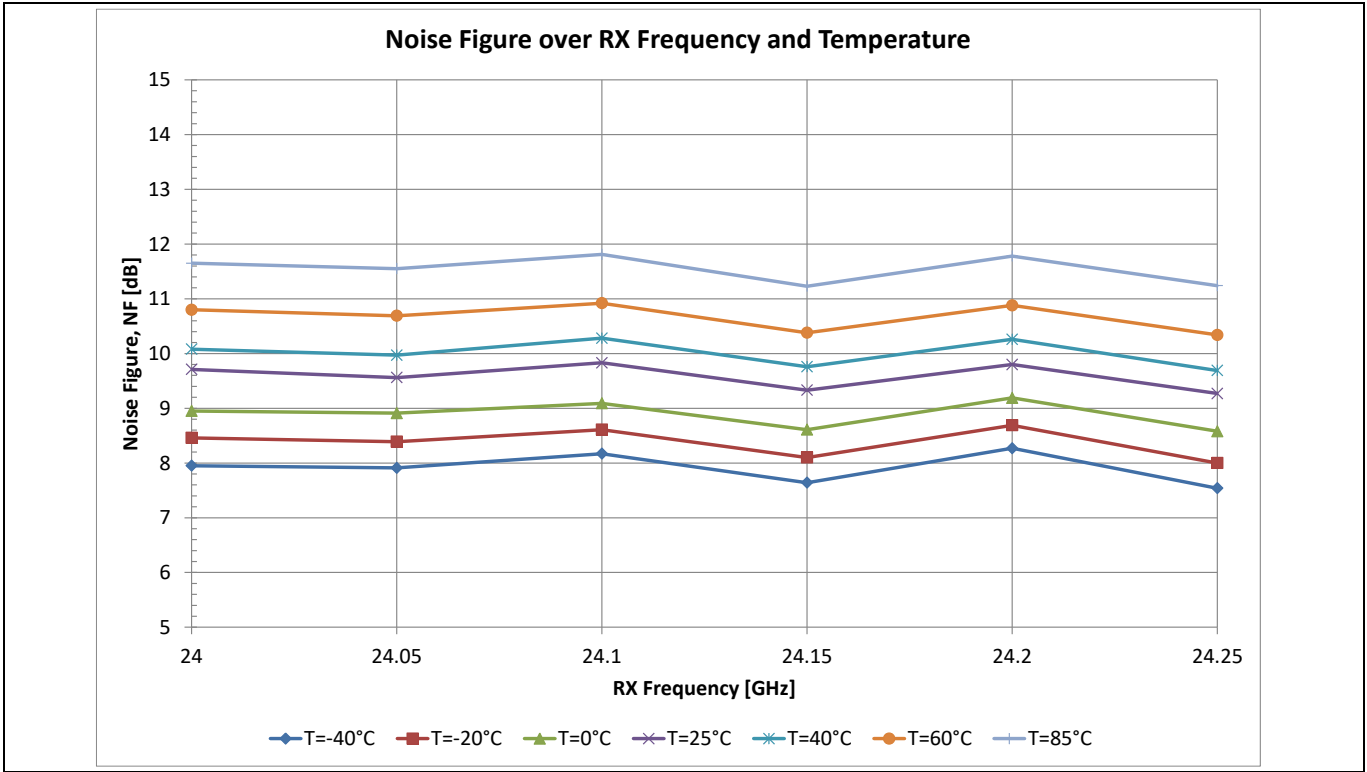


Figure 5 Noise figure vs. frequency

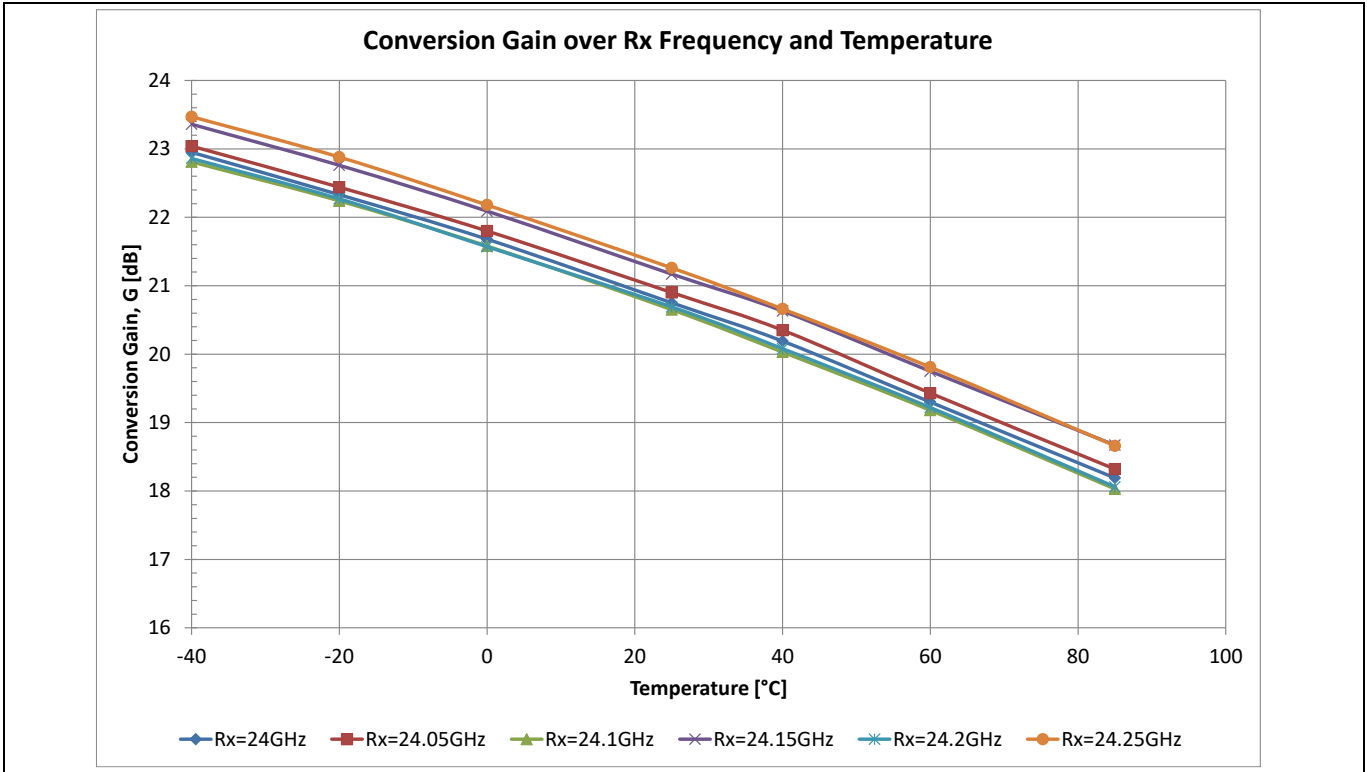


Figure 6 Conversion gain vs. temperature

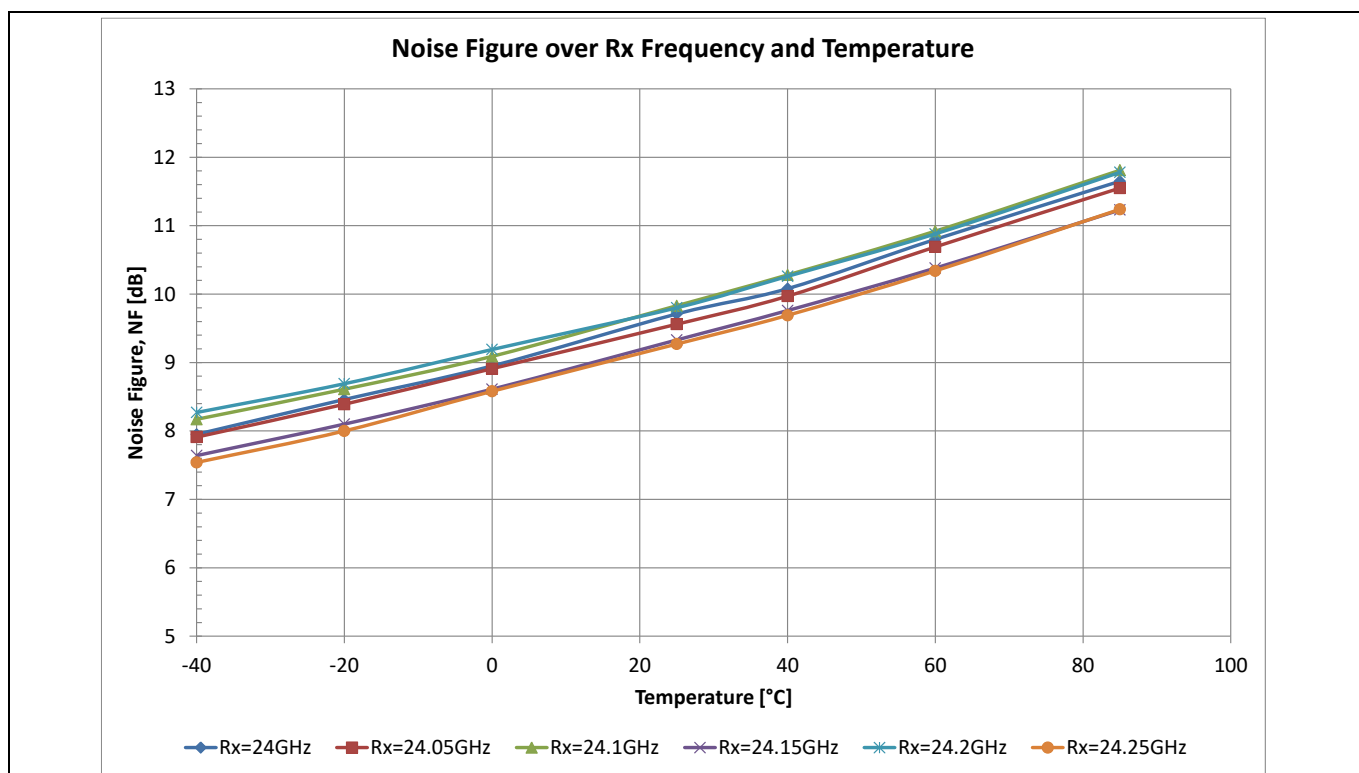


Figure 7 Noise figure vs. temperature

2.3 Voltage Controlled Oscillator (VCO)

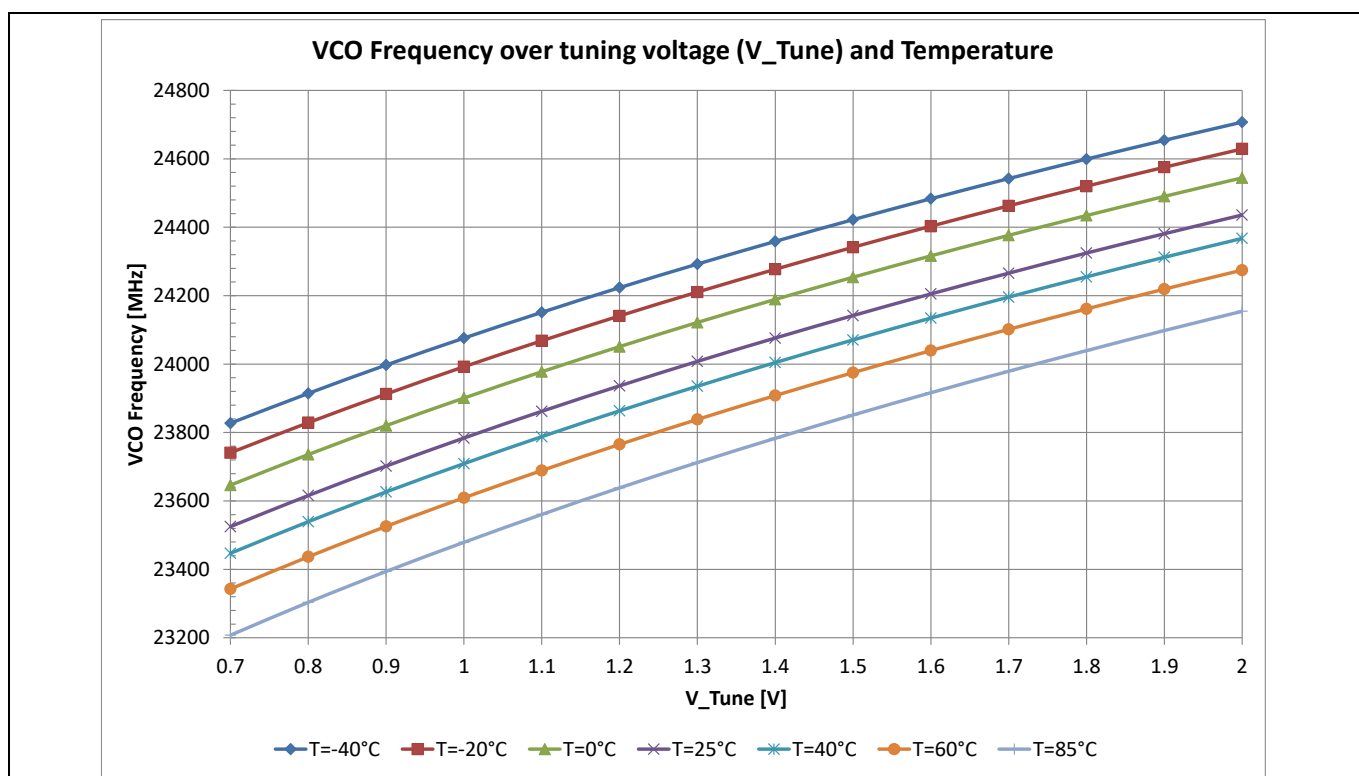


Figure 8 VCO frequency over tuning voltage and temperature

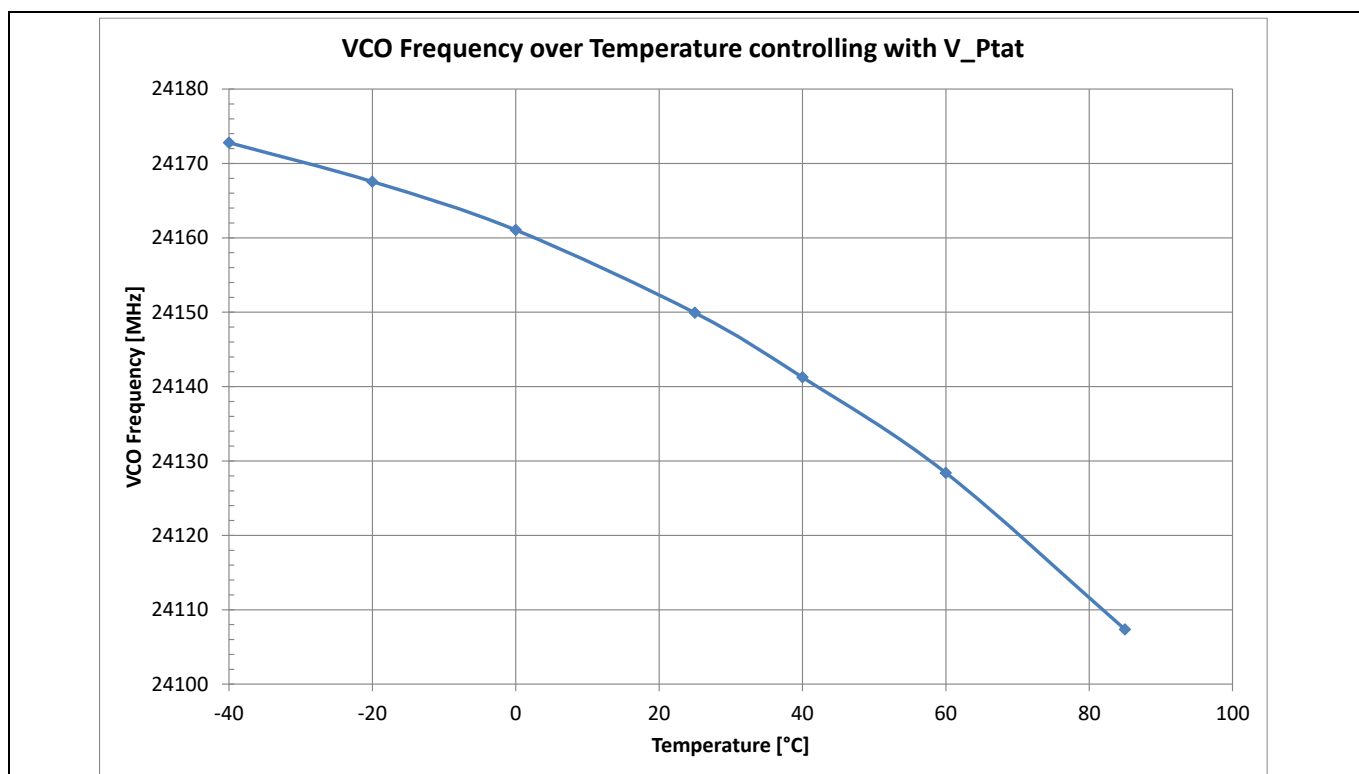


Figure 9 VCO frequency over temperature, VCO controlled by PTAT voltage source. Measured at random sample.

2.4 Proportional to Absolute Temperature (PTAT) voltage source

The PTAT voltage source generates a voltage V_{PTAT} at the V_{PTAT} pin (pin 15) which is proportional to the temperature of the chip. It is powered separate from VCC via the VCC_{PTAT} pin (pin 16).

The PTAT voltage source generates a tuning voltage for the VCO in Doppler mode (See Section 4.1).

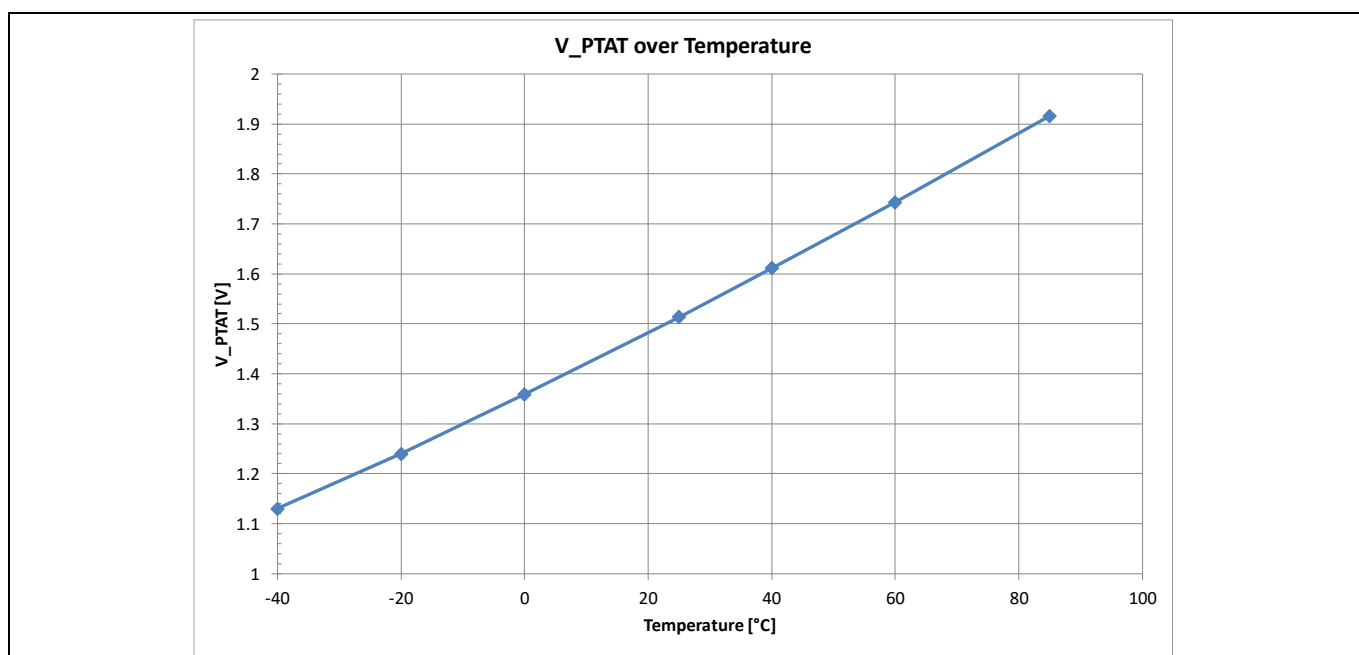


Figure 10 Voltage generated by PTAT voltage source vs. temperature for a random device.

2.5 Frequency divider

BGT24LTR11's frequency divider has two divider ratios, divide by 16 and divide by 8192 which result in output frequencies of 1.5 GHz and 3 MHz respectively.

Table 2 Setting the divider ratio

Divider ratio	Voltage at VCC_PTAT (pin 16)
16	< 0.8 V
8192	3.3 V

Setting the divider to a 3 MHz output will cause the PTAT to consume current. This ratio is usually used only in case of a software controlled VCO. In this use case, the V_{PTAT} is also required check the validity of the used look-up table (LUT), as explain in Section 4.3.

3 Evaluation board

3.1 Schematic diagram

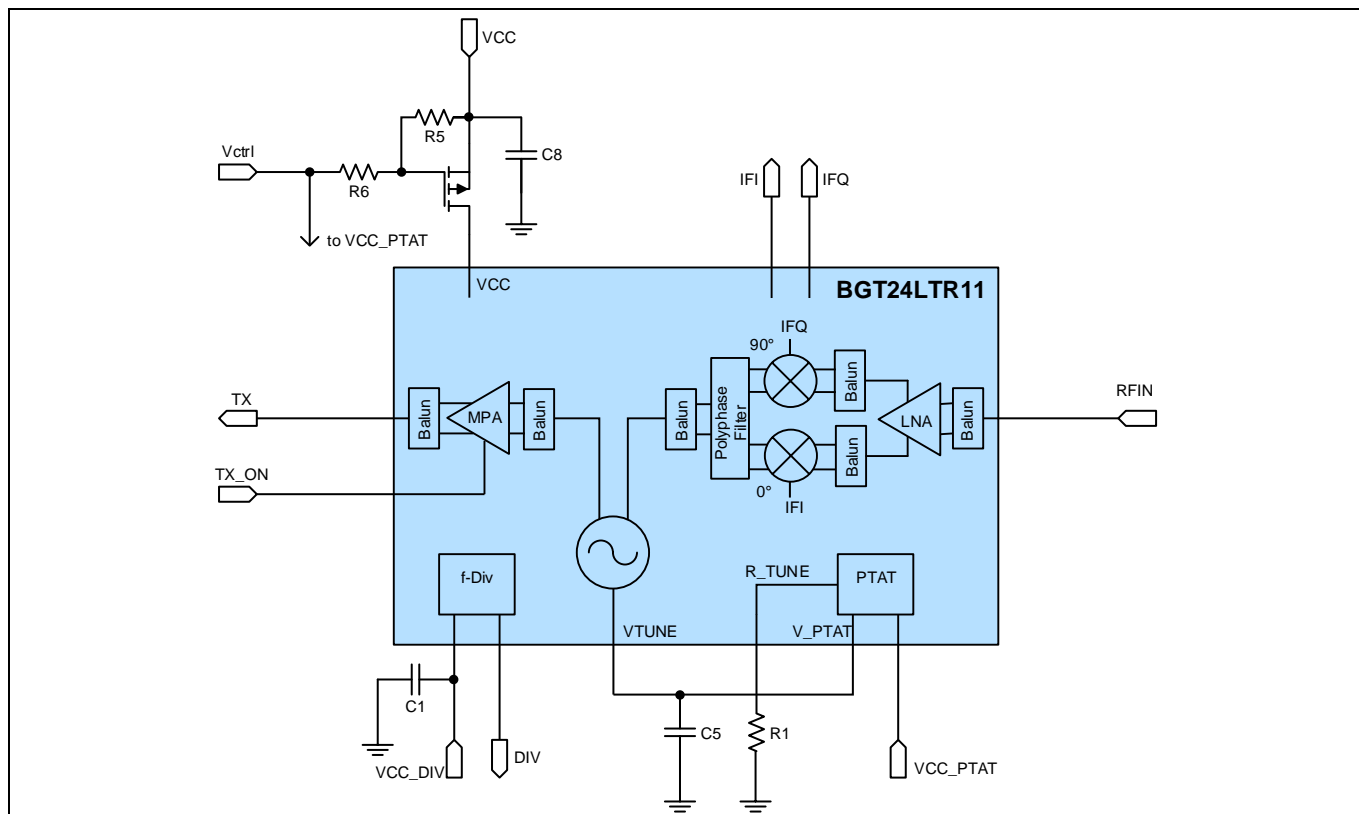


Figure 11 Evaluation board: schematic diagram

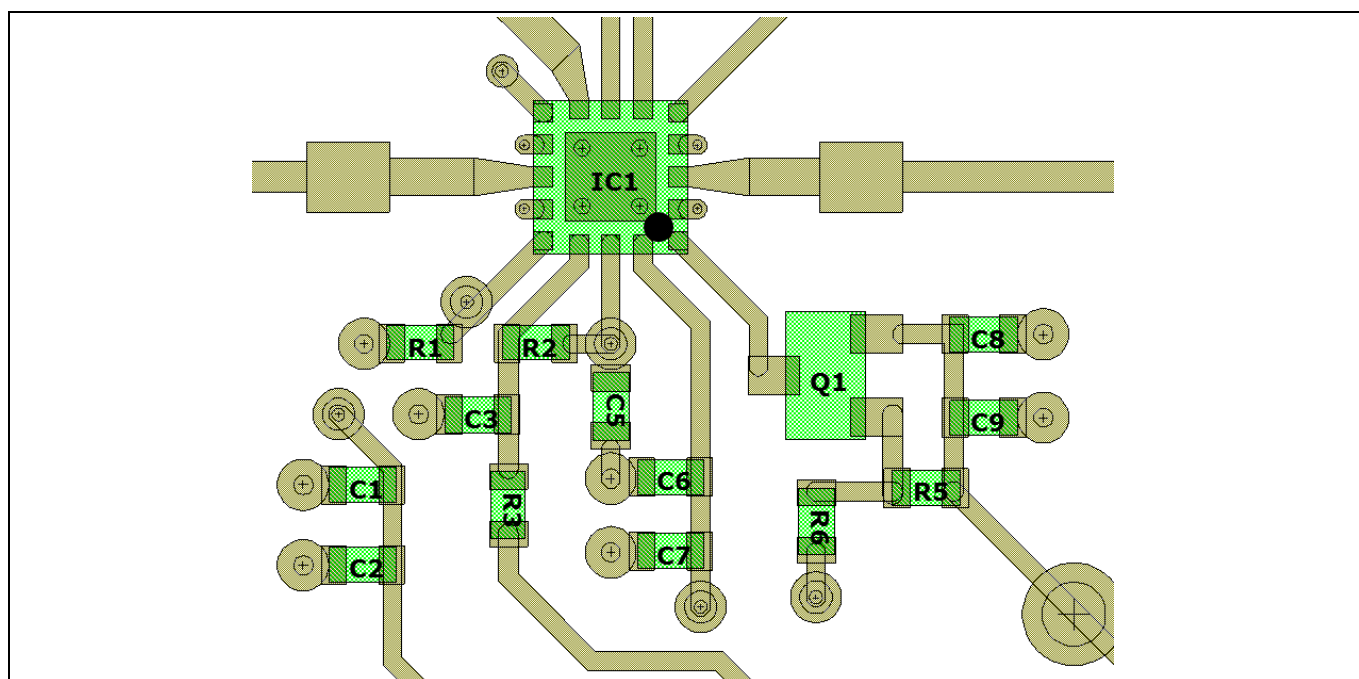


Figure 12 Evaluation board: component placement

Table 3 Bill of materials (BOM)

Designation	Part type	Value	Package	Manufacturer
C1, C5, C8	Chip capacitor	1 μ F	0402	Various
C2, C3, C6, C7, C9		DNP	0402	
R1	Chip resistor	16 k Ω	0402	Various
R2,R3	Chip resistor	0 Ω	0402	Various
R5	Chip resistor	100 k Ω	0402	Various
R6	Chip resistor	1 k Ω	0402	Various
Q1	p-MOSFET	BSS209PW	SOT-323	Infineon
IC1	Radar MMIC	BGT24LTR11N16	TSNP-16-9	Infineon

3.1.1 Matching structures

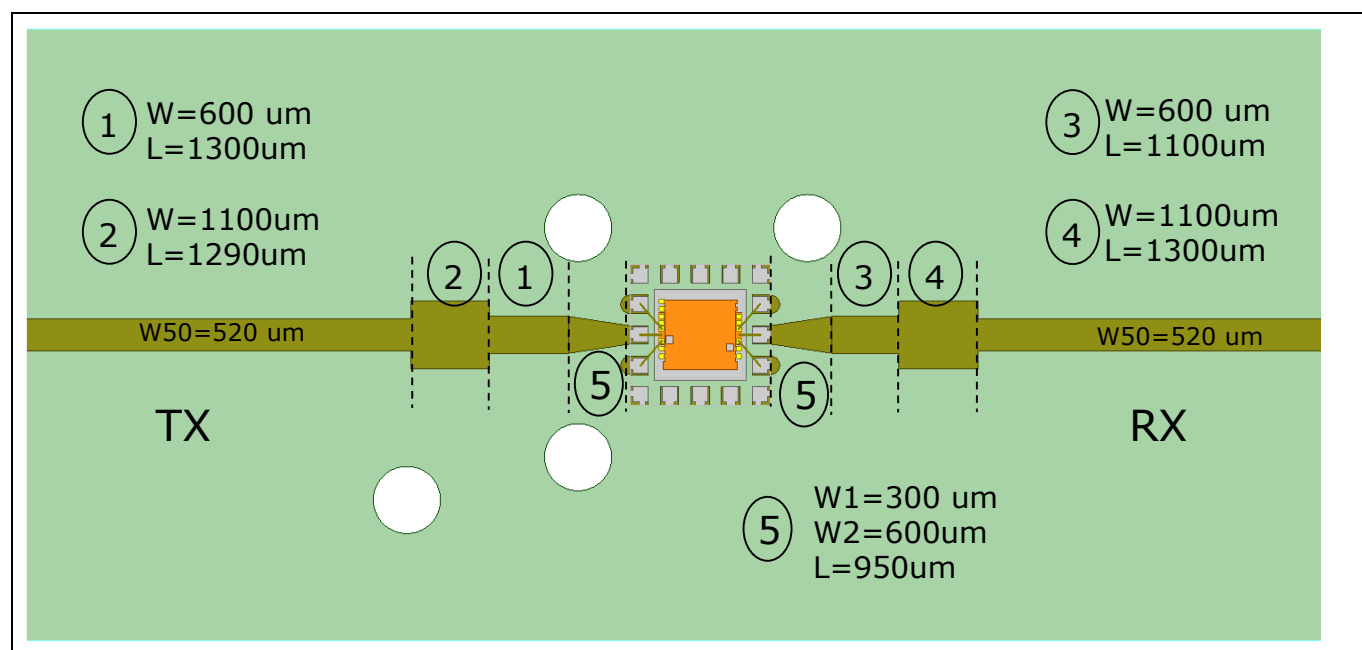


Figure 13 Evaluation board: matching structures on a Ro4350B substrate with a thickness of 0.254 mm

24 GHz Transceiver: BGT24LTR11

Evaluation board and system design

Evaluation board

3.2 Layout of evaluation board

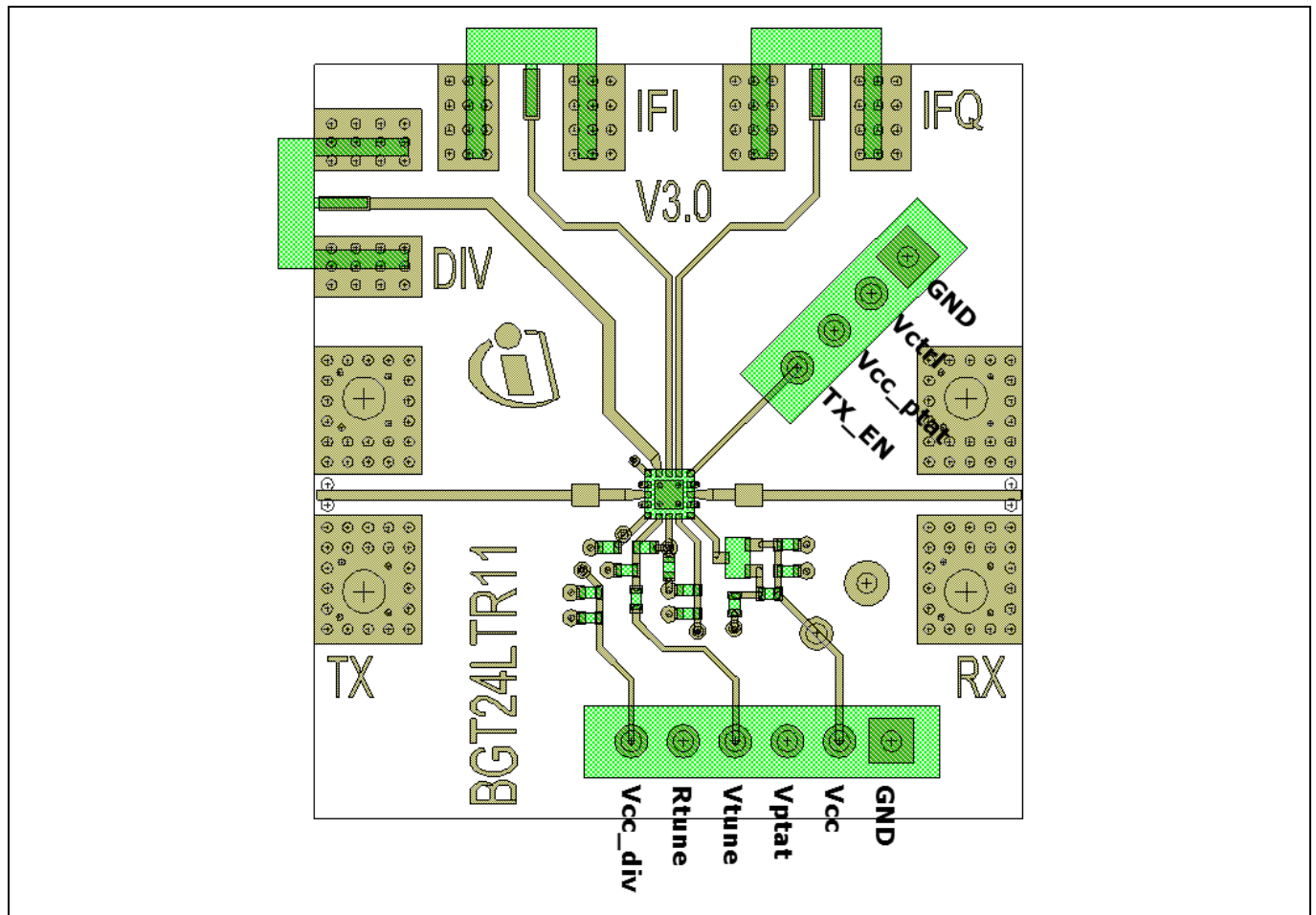


Figure 14 Evaluation board: layout with description of pin headers

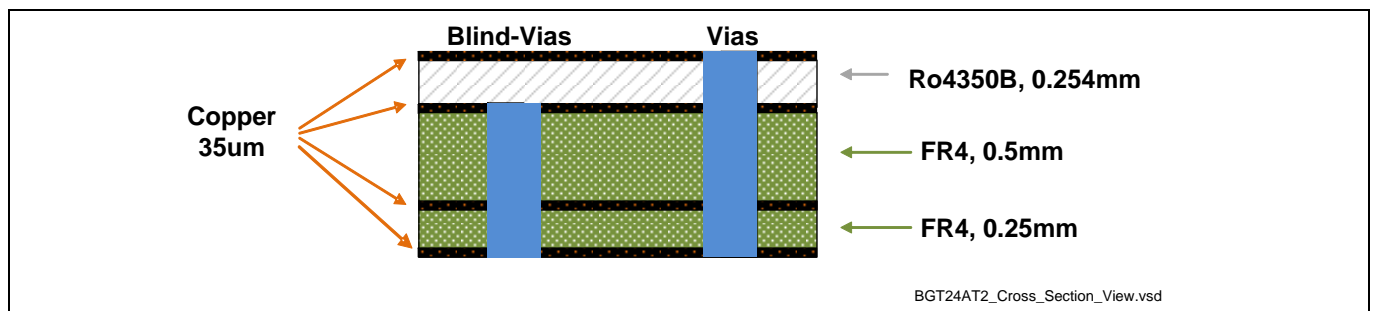


Figure 15 Evaluation board: layer stack

3.3 Layout version improving TX to RX isolation

The isolation between the TX port and the RX port on the standard evaluation board is typically about 25 dB. This isolation can be improved to 35dB by adding a grounded length of line at the ground pins next to the TX output pin as shown in Figure 16. Details of the used compensation structures can be found in Figure 17.

Table 4 TX to RX isolation

	Standard evaluation PCB	PCB with compensation structures
TX to RX isolation / dB	25	35

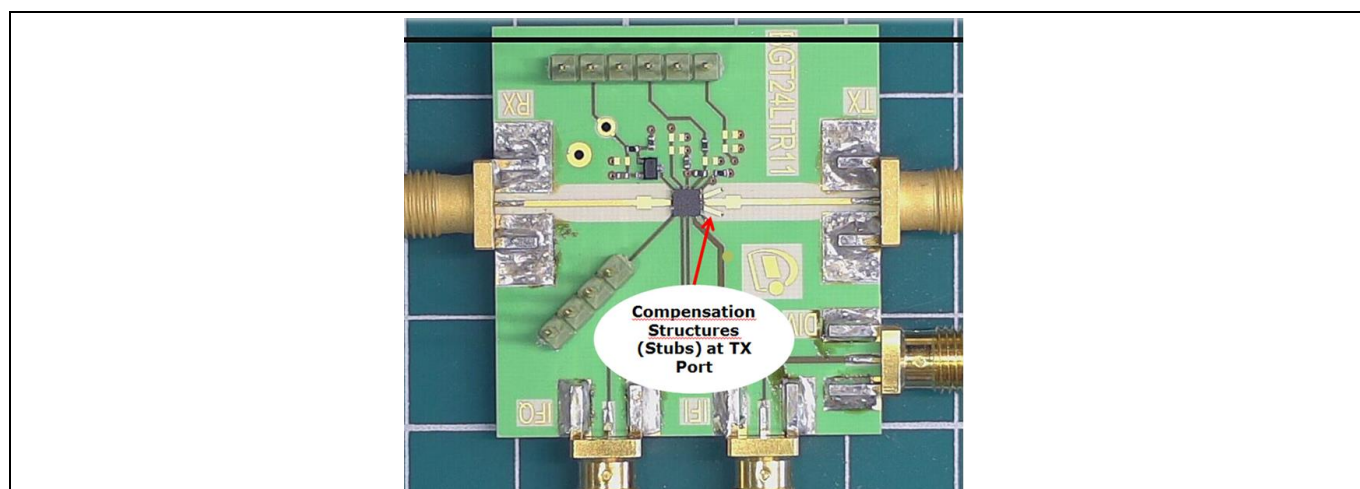


Figure 16 Evaluation board: addition of compensation structures to increase TX to RX isolation

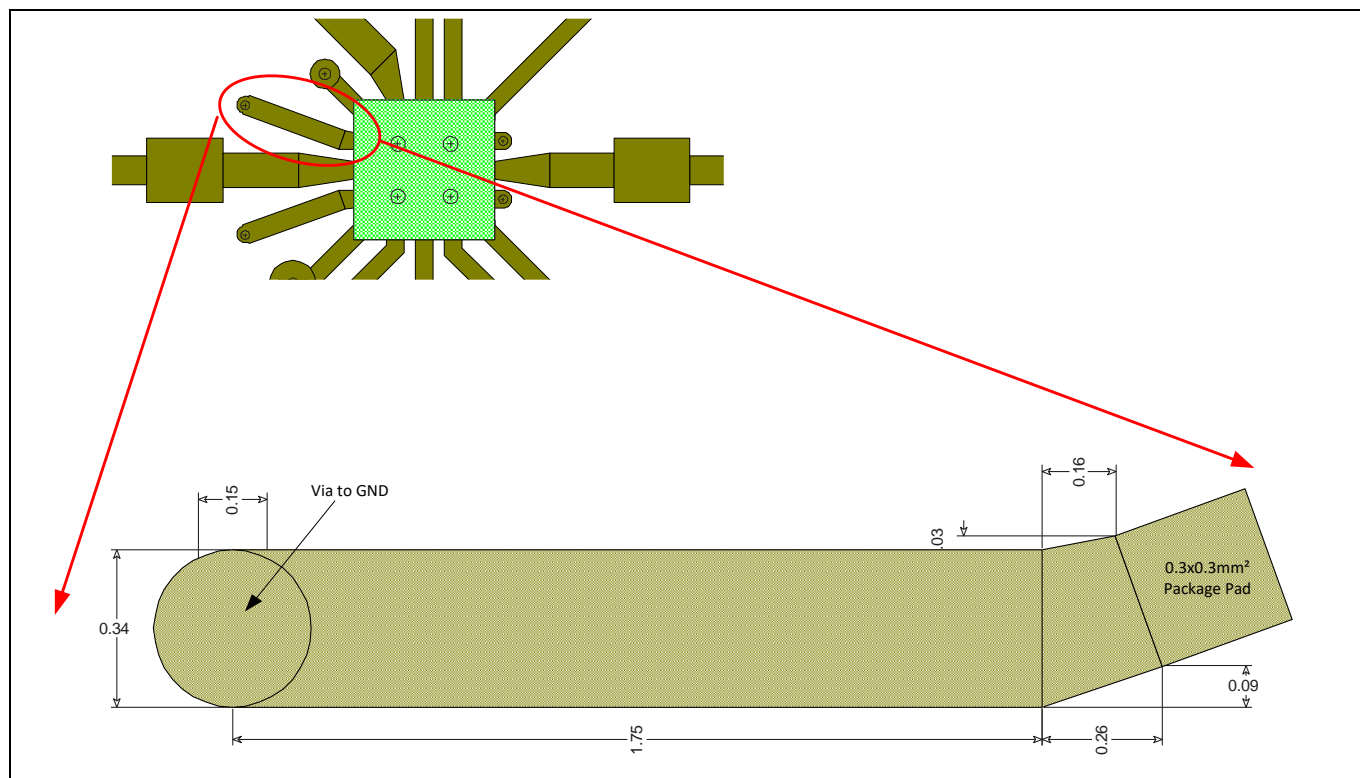


Figure 17 Evaluation board: compensation structures in detail. (Unit: mm)

VCO control

- Turning off VCC and VCC_PTAT reduces current consumption (45 mA and 1.5mA, respectively)
- The PTAT source generates noise at its output when running and this noise on the tuning voltage will degrade the signal to noise ratio (SNR) of the system. However, for some short range this SNR might still be acceptable.

Operation:

1. TX_ON = 0 V. Disables TX output to prevent out of band emissions.
2. Vctrl = 3.3 V. This turns on the PTAT source (VCC_PTAT = 3.3 V) while VCC line for the entire RF stage including the VCO is disconnected from the power supply.
3. Wait for C5 to be charged. At the start-up of the system when the capacitor is fully discharged this will require a longer time. During normal operation the capacitor is only slightly discharged and will be very quickly recharged.
4. Vctrl = 0 V. Turn off PTAT and turn on the rest of the chip (RF with VCO).
5. Wait for VCO to settle its frequency. Settling time of the VCO is maximum 100 ns.
6. TX_ON = 3.3 V. Enables TX output.
TX_ON should be delayed by about 200ns vs. RF section ON (Vctrl = 0 V) to keep TX signal clean.
7. Sample IF frequency.
8. Go to 1.

Further reduction of the power consumption is possible by introducing a time frame when both VCC and VCC_PTAT are disconnected. This would mean that VCC_PTAT needs to be disconnected from Vctrl and one more independent GPIO pin needs to be available at the microcontroller (MCU) in the system.

4.2 VCO control using a PLL

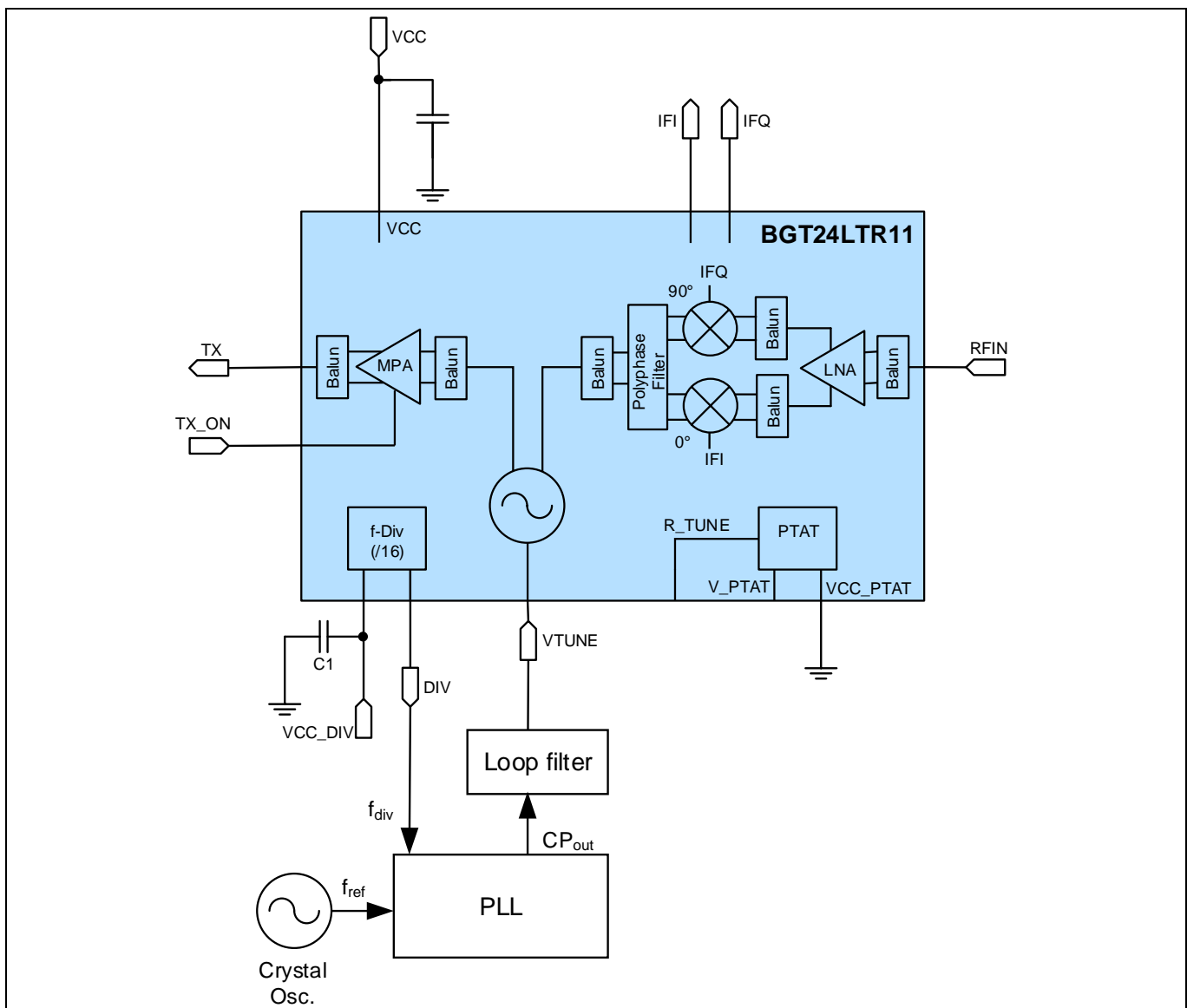


Figure 19 Block diagram: VCO control using a PLL

A PLL can be connected to the BGT24LTR11 to control the VCO as shown in Figure 19.

To implement this, the frequency divider needs to be set to a ratio of 16 by connecting VCC_PTAT to GND.

The VCO output is split into the TX antenna path and the Local Oscillator (LO) path. Furthermore the VCO output signal gets divided by a factor of 16 (prescaler), producing a 1.5 GHz divider output signal for the PLL.

In the PLL, further dividers (N-divider) are applied to the input divider signal to further reduce the frequency. The Phase Detector (PD) in PLL compares the N-divider output signal with the reference from a crystal oscillator to control the PLL Charge Pump (CP). The CP_{out} is converted into an analog VCO tuning signal (VTUNE) via the Loop Filter (LF). VTUNE finally controls the VCO frequency to achieve a full signal fit between N-divider output signal and the reference signal to achieve a frequency and phase lock.

4.3 VCO control using a software based open-loop concept

It is possible to control BGT24LTR11 using a software-based open loop concept. In this approach, a loop is needed with a voltage source and a feedback which is used to adapt the needed frequency changes. This implementation has the advantage of reducing the PCB space, BOM cost and power consumption by eliminating the HW PLL.

In this software based open-loop concept – often called as ‘Software PLL’ – there is no VCO phase and frequency locking to a reference signal. Frequency is measured periodically and VCO is tuned accordingly. VCO Phase Noise (PN) is comparable to the free-wheeling VCO (best case) and not improved like the HW PLL can do. However, VCO PN is less critical in Short Range Radar applications, because PN in the TX, RX and LO path stays mainly correlated for short target distances, resulting in a strong reduction of residual PN in the downmixed IF. (referring to: Range Correlation Effect).

Both Doppler radar and stepped-FMCW radar can be realized with this software based open-loop VCO adjustment/sweeping concept. System-performance might be lower than a HW PLL, but is often sufficient for a lot of applications like smart lighting or proximity detection etc.

4.3.1 Hardware setup

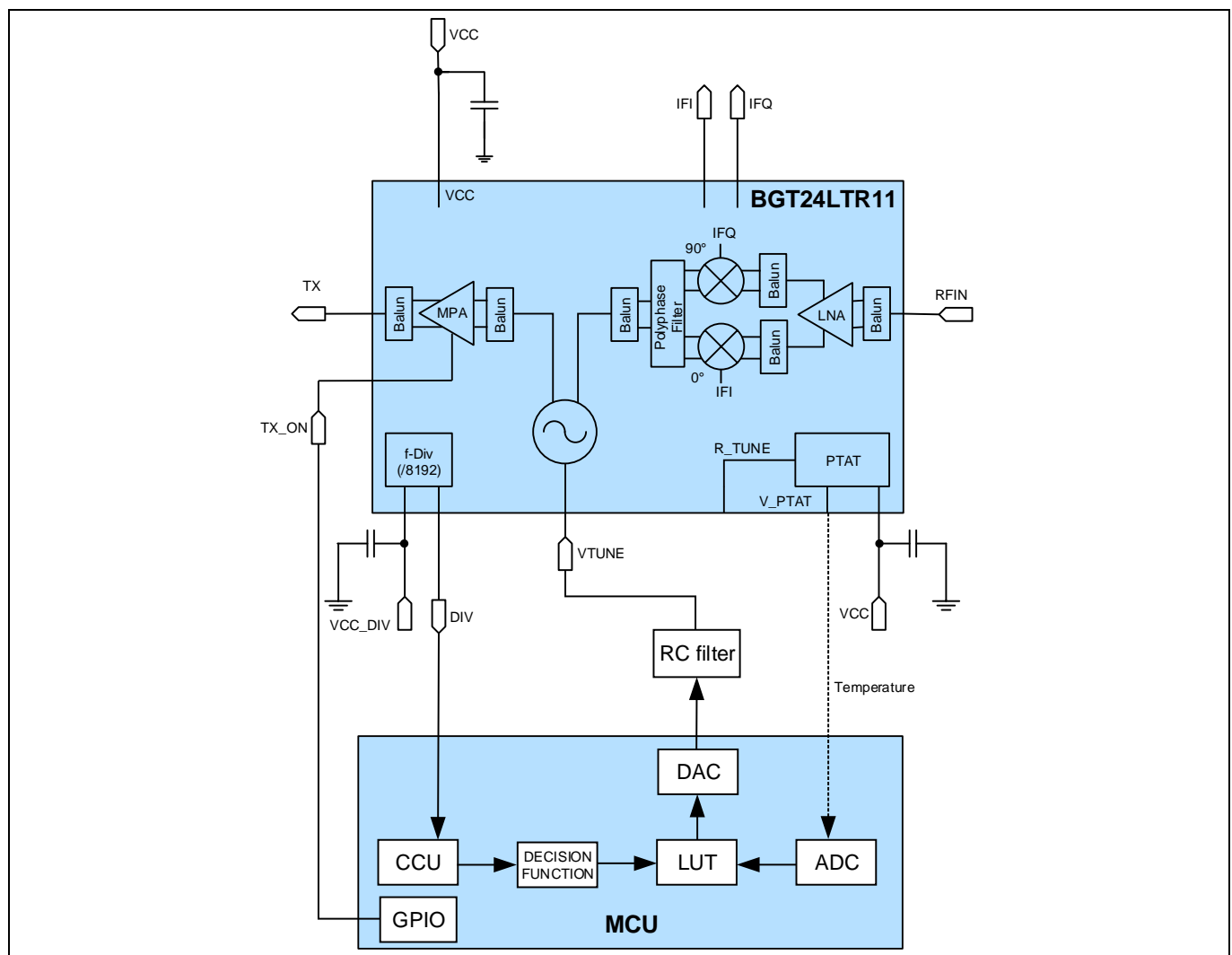


Figure 20 Block diagram: VCO control using a software-based open-loop concept

VCO control

Figure 20 shows a block diagram on how to set-up the system.

- Connect VCC_DIV and VCC_PTAT to VCC to set the divider ratio to 8192.
- Connect divider output to a Capture & Compare Unit (CCU) of the MCU to determine the frequency of the oscillator.
- Connect MCU's DAC output to the V_TUNE of BGT24LTR11 through a 2-stage RC filter to provide a tuning voltage to the VCO.
- The 2-stage RC DAC filter is required to filter the noise and reject the higher unwanted frequencies. It should be placed as close to the VCO V_TUNE input as possible.
- The design of this RC DAC filter is critical to avoid VCO modulation with noise and spurs. For a stepped-FMCW approach, the DAC filter needs to be optimized for the update rate based on the chirp time (T_c) and number of samples per chirp (N_{samples}). For example, for a $T_c = 1500$ ms and $N_{\text{samples}} = 256$, the update rate is $1500\text{ms}/256 = 6 \mu\text{s}$ (step-time). Therefore, the RC time constant for the DAC filter should be designed to settle at $5 \mu\text{s}$ (90...95% of desired voltage step). This lets the DAC's output voltage and consequently the VCO frequency to be in a steady state at the end of step-time when the baseband ADC is triggered for measurement.
- As an option, connect the V_PTAT output from BGT24LTR11 to an ADC channel of the MCU to determine the temperature of the chip. This would allow to compensate the frequency shift due to temperature changes and would reduce the need to re-calibrate the SW-PLL very frequently.

4.3.2 Concept

As shown in Figure 20, the DAC of the MCU is used to generate a tuning voltage for the VCO input. V_{tune} is generated by the DAC for the start frequency and then filtered in the RC-filter (2 stages). According to the V_{tune} input, the VCO produces the TX/LO signal. The VCO signal is also fed into a frequency divider and gets divided by a factor of 8192. This divided signal is captured by the CCU in the MCU. The divider output signal is measured by counting the number of rising/falling (or both) edges of the MCU's master clock inside a certain number of divider output signal periods (counting gate). The measured frequency is then compared with the required start frequency ($24.025\text{GHz}/8192 = 2.9327$ MHz). The difference between the measured and required frequency is then evaluated in the decision function. Depending on the result, the bit value gets adapted and the loop starts again until the measured and wanted frequency agree within a certain margin. This routine is repeated for the stop frequency as well ($24.225\text{GHz}/8192 = 2.9571$ MHz).

Note: To prevent out of band emissions a guard band of 25 MHz between ISM band edges and Start/Stop frequency of the stepped-FMCW sweep is implemented. Therefore the chirps have a bandwidth of 200 MHz ($24.025\text{GHz} - 24.225\text{GHz}$) and calibration is done every frame. The guard band would change depending on the circuitry implemented and how often the calibration is done.

The 200 MHz bandwidth is split up into a certain number of points per chirp (N_{samples}). N_{samples} is related to unambiguous range and therefore impacts the maximum range ($R_{\text{max}} = N_{\text{samples}} \cdot \Delta R$), where R_{max} is the maximum achievable range and ΔR is the range resolution.

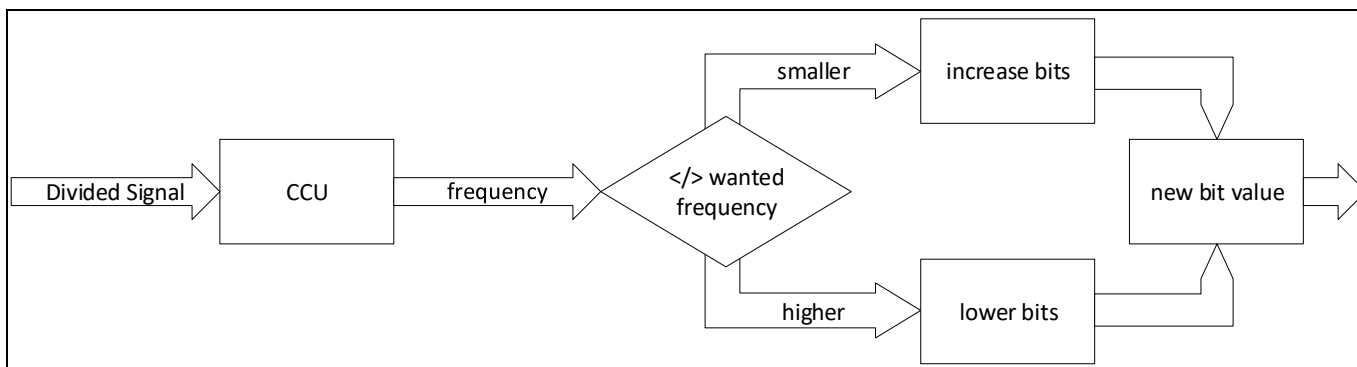


Figure 21 Decision function

The length of the counting gate has a strong impact on the accuracy of the VCO frequency measurement. At the start and at the end of the counting gate (N times the period of the divider output signal), there is a systematic error caused by the period of the MCU master clock. Longer counting gate time (i.e., more number of periods of the MCU master clock – e.g. 80MHz – are counted) results in a lower impact of this systematic error on VCO frequency measurement accuracy. However, longer counting gate time results in a longer ON time for the BGT24LTR11 and impacts the overall power consumption.

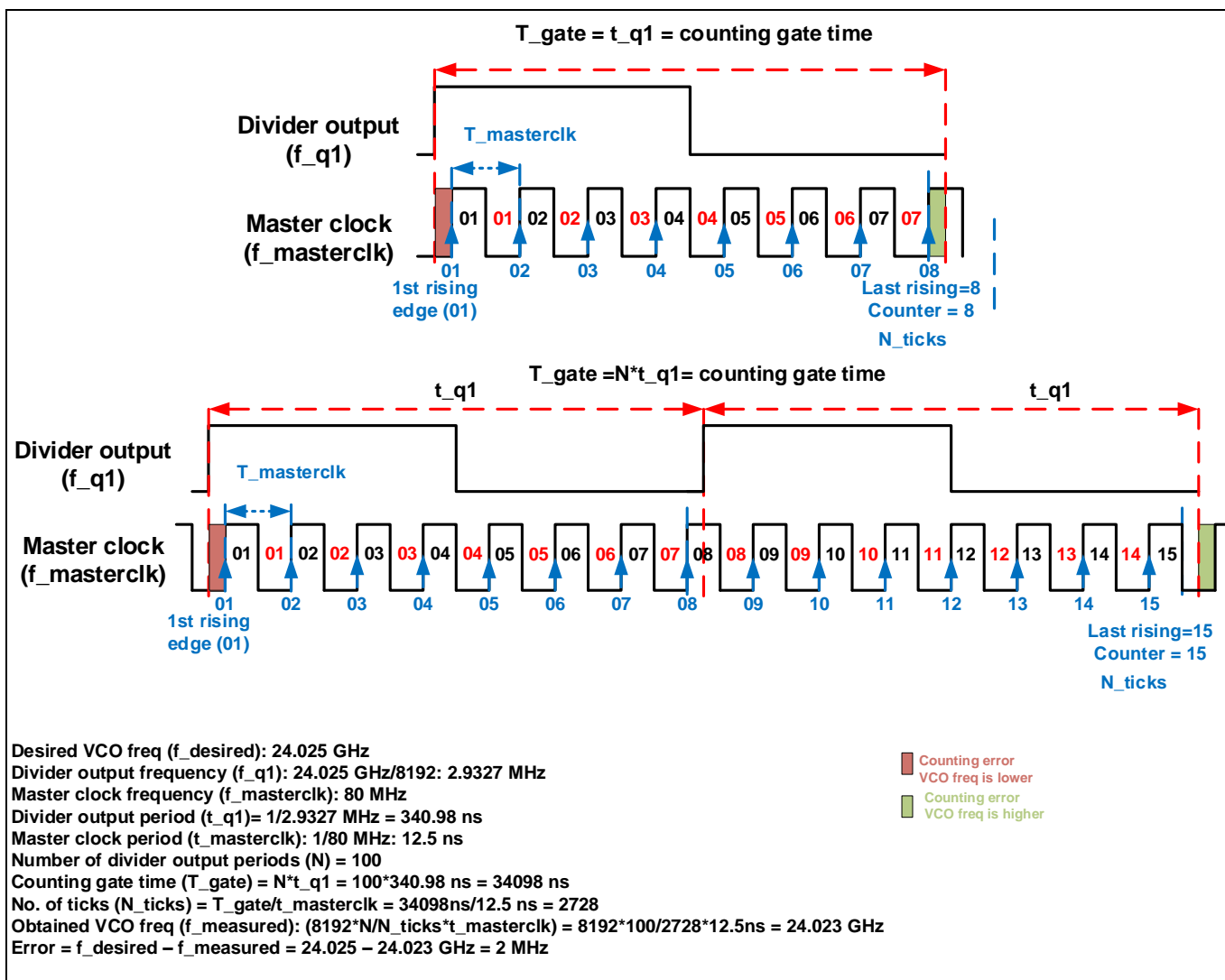


Figure 22 Systematic timing error at the start and the end of the counting gate

VCO control

For a divider output frequency of ~3MHz and a MCU master clock of 80 MHz, we recommend to count over 100 periods (N=100) of the divider output signal, to get a maximal frequency measurement error < 10 MHz.

Another way to reduce this systematic timing error would be to increase the master clock frequency (for example, a master clock of 120 MHz instead of 80 MHz will reduce the error as the T_{clock} time will be reduced from 12.5 ns to 8.3 ns, and the maximal frequency measurement error is < 6 MHz). However, higher master clock frequency leads to higher power consumption by the microcontroller.

*Note: To stay inside the ISM band during the frequency search process, the smart search for the start frequency begins always with a DAC value generating a VCO frequency **above** the desired start frequency. Similarly, stop frequency search should begin **below** the desired stop frequency.*

With the achieved start- and stop frequency DAC values (and Vtune values) a linear interpolation can be done and a look-up-table (LUT) "DAC value vs. VCO Frequency" is generated. The contents of the LUT are clocked (e.g. via DMA) to the DAC and hence provide the modulation of the VCO.

To further improve the linearity of the chirps, it is possible to do a search for three or more frequency points and perform a polynomial approximation between these points to fit the Vtune vs. VCO Frequency in a more precise non-linear LUT. Also, by utilizing chip's temperature information (e.g. via PTAT), the LUT can be re-calibrated only when there is a change in chip's temperature. This would reduce the need to calibrate the LUT very frequently.

4.3.3 Operation

1. To get best frequency measurement accuracy (NO VCO pulling effect), TX should remain ON during the frequency search process. VTUNE must keep the VCO in the ISM band all the time by following the 'smart search' methodology from Section 4.3.2.
2. Check the temperature of the chip using the V_{PTAT}. (if implemented)
3. Set the DAC to a fixed starting value for start frequency search to generate a VTUNE voltage for the VCO.
4. CCU measures the frequency of the divider output signal. The desired start frequency is already known and compared with the measured frequency. The DAC value is then adjusted using a decision function to achieve the best possible match for the desired frequency. (iterative frequency search process)
5. Once the DAC value for the start frequency is found, repeat the steps 3&4 to search the appropriate DAC value for the stop frequency.
6. Using these start and stop DAC values, generate a Look-Up Table (LUT) that gives the DAC values corresponding to different VCO frequencies.
7. Use the generated LUT for the modulation of the VCO by clocking the LUT values (e.g. via DMA) to the DAC. Feed the DAC output to the DAC filter. After the DAC filter output has settled on the step, take the ADC measurement and then move the DAC to the next LUT step, creating a stepped-FMCW chirp.
8. Check the temperature of the chip. If the temperature changed, or it is the beginning of a new frame go to 1 else go to 7 to generate the next chirp.

5 Authors

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Revision History

Major changes since the last revision

Page or Reference	Description of change
8 f	Corrections to PTAT source
Section 4	More detailed description of the VCO control through PTAT, PLL and Software-controlled loop

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